

# C3D08060G Silicon Carbide Schottky Diode

# Z-REC<sup>™</sup> RECTIFIER

600 V  $\mathbf{V}_{\mathsf{RRM}}$  $I_{\rm F}$  ( $T_{\rm c}$ =135°C) = 11 A 21 nC

## **Features**

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V<sub>F</sub>

## **Benefits**

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

# PIN 1O PIN 2O-

TO-263-2

**Package** 

## **Applications**

- Switch Mode Power Supplies
- **Power Factor Correction** 
  - Typical PFC P<sub>out</sub>: 800W-1600W
- **Motor Drives** 
  - Typical Power : 3HP-4HP

Part Number	Package	Marking
C3D08060G	TO-263-2	C3D08060

Halogen-Free

# **Maximum Ratings** (T<sub>c</sub> = 25 °C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	600	V		
$V_{RSM}$	Surge Peak Reverse Voltage	600	V		
V <sub>DC</sub>	DC Blocking Voltage	600	V		
$I_{_{\rm F}}$	Continuous Forward Current	24 11 8	А	T <sub>c</sub> =25°C T <sub>c</sub> =135°C T <sub>c</sub> =152°C	
$\boldsymbol{I}_{\text{FRM}}$	Repetitive Peak Forward Surge Current	57 36	А	$T_c$ =25°C, $t_p$ = 10 ms, Half Sine Wave, D=0.3 $T_c$ =110°C, $t_p$ =10 ms, Half Sine Wave, D=0.3	
$\mathbf{I}_{FSM}$	Non-Repetitive Peak Forward Surge Current	80 60	А	$T_c$ =25°C, $t_p$ = 10 mS, Half Sine Wave, D=0.3 $T_c$ =110°C, $t_p$ =10 ms, Half Sine Wave, D=0.3	
$\mathbf{I}_{FSM}$	Non-Repetitive Peak Forward Surge Current	220	А	$T_c = 25$ °C, $t_p = 10 \mu s$ , Pulse	
$P_{tot}$	Power Dissipation	107 46	W	T <sub>c</sub> =25°C T <sub>c</sub> =110°C	
$T_{_{\mathtt{J}}}$ , $T_{_{\mathtt{stg}}}$	Operating Junction and Storage Temperature	-55 to +175	°C		



## **Electrical Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub>	Forward Voltage	1.6 1.9	1.8 2.4	V	$I_F = 8 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 8 \text{ A } T_J = 175^{\circ}\text{C}$	
$I_R$	Reverse Current	10 20	50 200	μΑ	$V_R = 600 \text{ V } T_J = 25^{\circ}\text{C}$ $V_R = 600 \text{ V } T_J = 175^{\circ}\text{C}$	
Q <sub>c</sub>	Total Capacitive Charge	21		nC	$V_R = 600 \text{ V, } I_F = 8A$ $di/dt = 500 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	
С	Total Capacitance	441 39 33		pF	$V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 200 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 400 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$	

#### Note:

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Unit
$R_{_{ heta JC}}$	Thermal Resistance from Junction to Case	1.4	°C/W

## **Typical Performance**

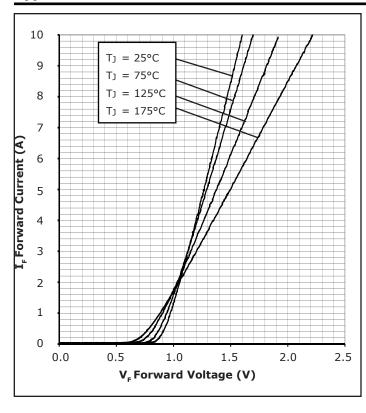


Figure 1. Forward Characteristics

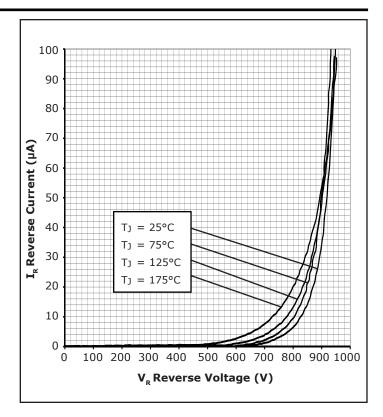
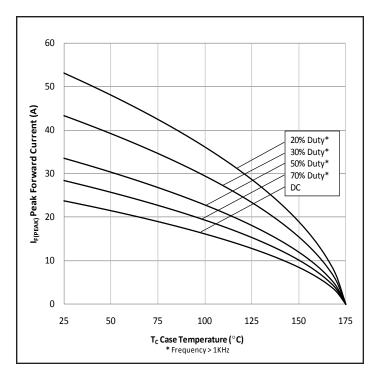


Figure 2. Reverse Characteristics

<sup>1.</sup> This is a majority carrier diode, so there is no reverse recovery charge.



## **Typical Performance**



400
350
300
250
150
100
50
1 100 1000
V<sub>R</sub> Reverse Voltage (V)

Figure 3. Current Derating

Figure 4. Capacitance vs. Reverse Voltage

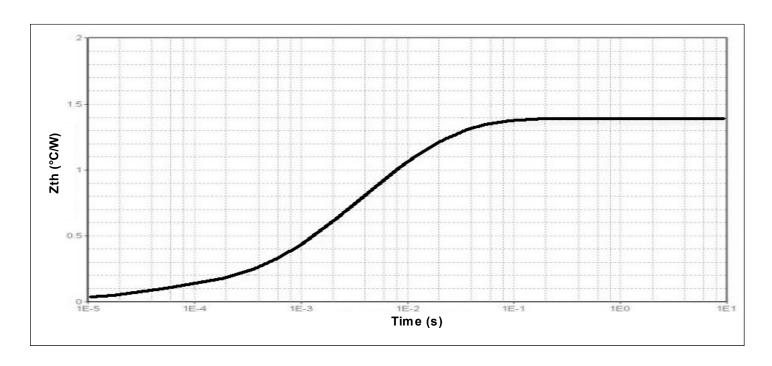


Figure 5. Transient Thermal Impedance



## **Typical Performance**

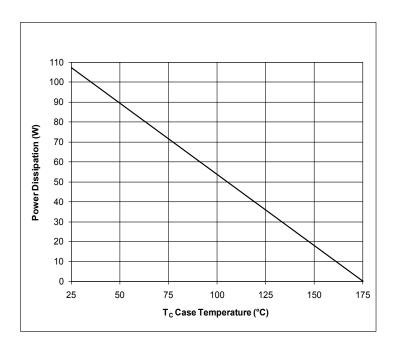
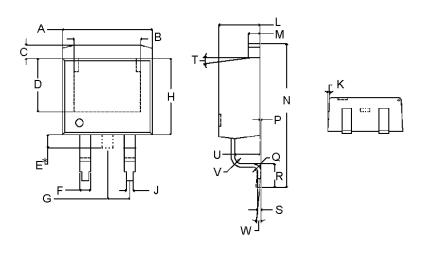


Figure 6. Power Derating

## **Package Dimensions**

Package TO-263-2



O CASE

POS	Inc	hes	Millimeters		
PUS	Min		Min	Max	
А	.396	.406	10.058	10.312	
В	.295	.335	7.493	8.509	
С	.05	.065	1.27	1.651	
D	.25	.27	6.35	6.858	
E*	0.00	.07	0.00	1.778	
F	.048	.062	1.219	1.575	
G	.100	TYP	2.540	) TYP	
Н	.35	.37	8.890	9.398	
J	.028	.034	.711	.864	
К	2°	5°	2°	5°	
L	.170	.180	4.318	4.572	
М	.045	.055	1.143	1.397	
N	.595	.615	15.113	15.621	
Р	0.00	0.10	0.00	2.54	
Q	R0.018 TYP	R0.022 TYP	R0.457 TYP	R0.559 TYP	
R	.090	.110	2.286	2.794	
S	.013	.02	.330	.508	
Т	6.5°	8.5°	6.5°	8.5°	
U	.100	.107	2.540	2.718	
W	_	5.0°	_	5.0°	

NI	ata	
IΝ	ote	

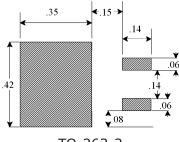
<sup>\*</sup> Tab "E" may not be present

PIN 1 O-

PIN 2O-



## **Recommended Solder Pad Layout**



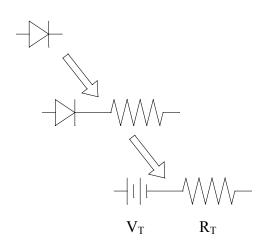
TO-263-2

Part Number	Package	Marking
C3D08060G	TO-263-2	C3D08060

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power\_app\_notes/soldering



## **Diode Model**



$$Vf_T = V_T + If * R_T$$

$$V_T = 0.93 + (T_J^* - 9.3*10^{-4})$$
  
 $R_T = 0.058 + (T_J^* 5.7*10^{-4})$ 

Note:  $T_i$  = Diode Junction Temperature In Degrees Celsius



#### **Notes**

#### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

#### REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

• This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, air traffic control systems, or weapons systems.